

IN THE CLAIMS:

Claims 1 through 6 and 9 through 10 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) An electronic device package comprising:
a transparent substrate structure;
~~a secondary~~ at least one secondary substrate having a first surface secured to a surface of the transparent ~~substrate, substrate structure,~~ a central aperture covered by the transparent ~~substrate, substrate structure,~~ and a plurality of conductive traces formed around the central aperture, each conductive trace of the plurality of conductive traces having a first attachment point and a second attachment point on a second surface of the at least one secondary substrate;
~~an optically~~ at least one optically interactive electronic device having at least one bond pad, the at least one optically interactive electronic device mounted to the at least one secondary substrate by a bond between the first attachment point of a conductive trace of the plurality of conductive traces and the at least one bond pad; and
a discrete conductive element attached to the second attachment point of the conductive trace, the discrete conductive element extending outwardly from the at least one secondary substrate within an outside perimeter thereof from the second attachment point in a direction perpendicular to a plane of the at least one secondary substrate and to a level beyond a back surface of the at least one optically interactive electronic device.
2. (Currently Amended) The electronic device package according to claim 1, wherein the second attachment points of the plurality of conductive traces are located in at least one row extending adjacent a perimeter portion of the second surface of the at least one secondary substrate.

3. (Currently Amended) The electronic device package according to claim 2, wherein the second attachment points of the plurality of conductive traces are located in multiple rows extending adjacent the perimeter portion of the second surface of the at least one secondary substrate.

4. (Currently Amended) The electronic device package according to claim 1, wherein the at least one secondary substrate comprises one of a printed circuit board, a polyimide film, a ceramic and silicon.

5. (Currently Amended) The electronic device package according to claim 1, wherein the outside perimeter of the at least one secondary substrate is substantially equal to an outside perimeter of the transparent ~~substrate~~substrate structure.

6. (Currently Amended) The electronic device package according to claim 1, further comprising:
a bead of sealant material contacting at least one side of the at least one optically interactive electronic device and the second surface of the at least one secondary substrate.

7. (Original) The electronic device package according to claim 6, wherein the bead of sealant material comprises one of epoxy and silicone.

8. (Previously Presented) The electronic device package according to claim 1, wherein the discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.

9. (Currently Amended) The electronic device package according to claim 1, wherein the at least one optically interactive electronic device comprises an image sensor.

10. (Currently Amended) The electronic device package according to claim 1, wherein the at least one secondary substrate comprises a plurality of secondary substrates, each secondary substrate of the plurality secured to the surface of the transparent substrate structure, and the at least one optically interactive electronic device comprises a plurality of optically interactive electronic devices.~~transparent substrate comprises a single substrate having multiple optically interactive electronic device packages mounted thereto.~~